

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS165N08S5N029	**Issued**	16. May 2021
MA#	MA005344625		
Package	PG-HSOG-8-1	**Weight***	702.42 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.197	0.46	0.46	4552	4552
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		191	
	non noble metal	copper	7440-50-8	134.219	19.11	19.14	191081	191329
wire	non noble metal	aluminium	7429-90-5	9.790	1.39	1.39	13938	13938
encapsulation	inorganic material	zincoxide	1314-13-2	2.676	0.38		3810	
	miscellaneous	miscellaneous	-	10.704	1.52		15238	
	plastics	epoxy resin	-	40.138	5.71		57143	
	inorganic material	silicondioxide	60676-86-0	214.070	30.48	38.09	304761	380952
leadfinish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11829	11829
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	312	313
solder	non noble metal	tin	7440-31-5	0.057	0.01		81	
	noble metal	silver	7440-22-4	0.071	0.01		102	
	non noble metal	lead	7439-92-1	2.730	0.39	0.41	3887	4070
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		118	
	non noble metal	iron	7439-89-6	0.276	0.04		393	
	non noble metal	copper	7440-50-8	275.705	39.25	39.30	392506	393017
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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